

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

5 Claim 1 (Currently amended): A ~~multiple chips~~multi-chip image sensor module, comprising:

a first substrate, which has an upper surface and a lower surface, wherein the upper surface is formed with a plurality of first connectedconnecting ends, and the lower surface is formed with a plurality of second connectedconnecting ends; □

10 a photosensitive chip, which is arranged aton the upper surface of the first substrate, and electrically connected to the first connectedconnecting ends by a plurality of first wires; □

15 a lens holder formed with a penetrateholethrough hole at a center central thereof, wherein an internal thread beingis formed on an the inner wall of the penetrateholethrough hole, and the lens holder beingis mounted on the upper surface of the first substrate to encapsulate the photosensitive chip; □

20 a lens barrel arranged within the penetrateholethrough hole of the lens holder and is-formed with an external thread, which is screwed to the internal thread of the lens holder, wherein the lens barrel is being-formed with a chamber and an opening communicating with the chamber; □

25 an aspheric lens and a transparent layer placed within the chamber; □
a second substrate having formed with a first surface on which a plurality of signal output ends are formed, and a second surface on which a plurality of signal input ends are formed, wherein the first surface of the second substrate is mounted on the lower surface of the first substrate, and surface, then the signal output ends are electrically connected the second connecting ends of the first substrate; and surface □

30 a lower chip located on the second surface of the second substrate and is electrically connected to the signal input ends of the second substrate.

Claim 2 (Currently amended): The ~~multiple chips~~multi-chip image sensor

module according to claim 1, wherein the second substrate is a flexible/hard combination board, which includes a flexible board and a hard board, the lower chip is mounted on the flexible board, and the hard board is mounted on the lower surface of the first substrate.

5 Claim 3 (Currently amended): The ~~multiple chips~~-multi-chip image sensor module according to claim 1, wherein the lower chip is electrically connected to the signal input ends by second wires.

10 Claim 4 (Currently amended): The ~~multiple chips~~-multi-chip image sensor module according to claim 1, ~~wherein further includes a expose~~further comprising a resin layer for encapsulating the lower chip.

Claim 5 (Currently amended): The ~~multiple chips~~-multi-chip image sensor module according to claim 1, wherein the lower chip is a signal processor digit and the image sensor module further comprises ~~further includes a expose~~a resin layer for encapsulating the lower chip.